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U.S. Ser. No. 10/629,285

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JUL 0 6 2006

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CLAIM AMENDMENTS

- 1. (Currently Amended) A method of fabricating a thermal management device, comprising the steps of:
- a) using a solid-state consolidation process to deposit a plurality of first material layers exhibiting a relatively-high degree of thermal conductivity; and
- b) separating the first material layers with a different, second material having a desired physical property.
- 2. (Currently Amended) The method of claim 1, wherein the desired physical property is a relatively high coefficient of thermal expansion.
 - 3. (Original) The method of claim 1, wherein the second material is air.
 - 4. (Original) The method of claim 1, wherein the first material is copper.
 - 5. (Original) The method of claim 1, wherein the first material is aluminum.
- 6. (Original) The method of claim 1, wherein the first material is in the form of a mesh or screen.
 - 7. (Original) The method of claim 1, wherein the second material is molybdenum.

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CLAIM AMENDMENTS

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- 1. (Currently Amended) A method of fabricating a thermal management device, comprising the steps of:
- a) using a solid-state consolidation process to deposit a plurality of first material layers exhibiting a relatively-high degree of thermal conductivity; and
- b) separating the first material layers with a different, second material having a desired physical property.
- 2. (Currently Amended) The method of claim 1, wherein the desired physical property is a relatively high coefficient of thermal expansion.
 - 3. (Original) The method of claim 1, wherein the second material is air.
 - (Original) The method of claim 1, wherein the first material is copper. 4.
 - 5. (Original) The method of claim 1, wherein the first material is aluminum.
- 6. (Original) The method of claim 1, wherein the first material is in the form of a mesh or screen.
 - 7. (Original) The method of claim 1, wherein the second material is molybdenum.
- (Currently Amended) The method of claim 1, wherein the second material is 8. Kovar an iron-nickel-cobalt alloy.
- 9. (Original) The method of claim 1, wherein the solid-state consolidation process is an ultrasonic consolidation process.

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- 10. (Original) The method of claim 1, wherein the solid-state consolidation process includes electrical resistance consolidation.
- 11. (Original) The method of claim 1, wherein the solid-state consolidation process includes frictional consolidation.
- 12. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 1.
- 13. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 2.
- 14. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 3.
- 15. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 4.
- 16. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 5.
- **17**. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 6.
- 18. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 7.
- 19. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 8.

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- 20. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 9.
- 21. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 10.
- 22. (Withdrawn) A thermal management device fabricated in accordance with the method of claim 11.
- 23. (Original) The method of claim 1, wherein the material layers form a cooling channel.
- 24. (Original) The method of claim 1, furthering including the addition of wicking material.
- 25. (Original) The method of claim 1, furthering including the step of embedding a sensor into the device.
- 26. (Original) The method of claim 1, furthering including the step of embedding a fan, heat pump, or other active device to increase heat dissipation rate into the device.
 - 27. (Original) The method of claim 1, wherein the material layers form a thermal bus.